



FOR IMMEDIATE RELEASE

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**AEHR TEST SYSTEMS RECEIVES ORDER
FOR FOX FULL WAFER TEST & BURN-IN SYSTEM**

Fremont, CA (March 19, 2003) – Aehr Test Systems (Nasdaq: AEHR), a leading supplier of semiconductor test and burn-in equipment, today announced that a leading semiconductor manufacturer has placed an order for the new 300mm FOX™ full wafer contact test and burn-in system. The system is expected to ship in late calendar 2003.

“The new 300mm FOX system makes use of Aehr Test’s proprietary interconnect and parallel test technologies developed for our FOX full wafer contact product line,” said C.J. Meurell, president and chief operating officer of Aehr Test. “We believe wafer level test and burn-in, coupled with Design For Test (DFT), will create significant cost reduction for the back-end test and burn-in process.”

“We are very excited by this order and the potential market opportunities for our FOX full wafer contact products,” commented Rhea Posedel, chairman and chief executive officer of Aehr Test. “Device manufacturers have shown interest in our FOX family of products for a wide range of applications, from reliability process monitors for faster qualifications of new 300mm fabs, to cost-effective test and burn-in solutions for wafers using DFT test strategies. We expect that our FOX products will fuel our growth over the long term.”

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a leading worldwide provider of systems for burning-in and testing DRAM and logic integrated circuits and has an installed base of more than 2,000 systems worldwide. Aehr Test has developed and introduced several innovative products, including the FOX, MTX, MAX3 and MAX4 systems and the DiePak® carrier. The FOX system is a full wafer contact test and burn-in system. The MTX system is a massively parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX system can effectively burn-in and functionally test sophisticated devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die.

Safe Harbor Statement

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding industry growth and customer demand for Aehr Test's products. Actual results may vary from projected results. These risks and uncertainties include economic conditions in Asia and elsewhere, world events, acceptance by customers of the FOX, MTX, MAX and DiePak technologies, the ability of the Company to gain business in China, the Company's development and manufacture of a commercially successful wafer-level burn-in system, and the potential emergence of alternative technologies, which could adversely affect demand for Aehr Test's products in calendar year 2003. See Aehr Test's recent 10-K and 10-Q reports filed with the SEC for additional risks affecting Aehr Test.

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